

Ferrites and accessories

EP 7 Core and accessories

Series/Type: **B65839, B65840**

Date: February 2025

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EP 7

Core

B65839

- To IEC 63093-5
- For transformers featuring high inductance and low overall height
- For power applications
- Delivery mode: sets

Magnetic characteristics (per set)

$$\Sigma l/A = 1.52 \text{ mm}^{-1}$$

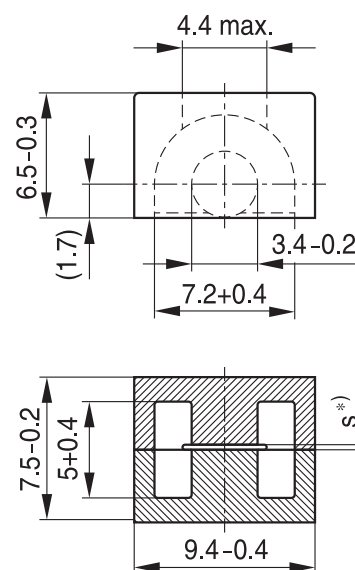
$$l_e = 15.7 \text{ mm}$$

$$A_e = 10.3 \text{ mm}^2$$

$$A_{\min} = 8.5 \text{ mm}^2$$

$$V_e = 162 \text{ mm}^3$$

Approx. weight 1.4 g/set



*) gapped (one-sided)

FEP0115-F-E

Gapped (A_L values/air gaps examples)

Material	A_L value nH	s approx. mm	μ_e	Ordering code
T38	63 $\pm$ 3%	0.20	76	B65839A0063A038
	100 $\pm$ 3%	0.13	121	B65839A0100A038
	160 $\pm$ 5%	0.08	194	B65839A0160J038
	200 $\pm$ 6%	0.06	243	B65839A0200C038
	250 $\pm$ 7%	0.05	303	B65839A0250E038
T57	63 $\pm$ 3%	0.20	76	B65839A0063A057
	100 $\pm$ 3%	0.13	121	B65839A0100A057
	160 $\pm$ 5%	0.08	194	B65839A0160J057
	200 $\pm$ 6%	0.06	243	B65839A0200C057
	250 $\pm$ 7%	0.05	303	B65839A0250E057
N45	63 $\pm$ 3%	0.20	76	B65839A0063A045
	100 $\pm$ 3%	0.13	121	B65839A0100A045
	160 $\pm$ 5%	0.08	194	B65839A0160J045
	200 $\pm$ 6%	0.06	243	B65839A0200C045
	250 $\pm$ 7%	0.05	303	B65839A0250E045
N87	63 $\pm$ 3%	0.20	76	B65839A0063A087
	100 $\pm$ 3%	0.12	121	B65839A0100A087
	160 $\pm$ 5%	0.07	194	B65839A0160J087
	200 $\pm$ 6%	0.06	243	B65839A0200C087
	250 $\pm$ 7%	0.05	303	B65839A0250E087

EP 7
Core
B65839
Ungapped

Material	A _L value nH	μ _e	P _V W/set	Ordering code
N95	1300 +30/–20%	1580	< 0.08 (200 mT, 100 kHz, 25 °C) < 0.075 (200 mT, 100 kHz, 100 °C)	B65839A0000R095
N45	1500 +30/–20%	1820		B65839A0000R045
N30	2000 +30/–20%	2430		B65839A0000R030
T57	1500 +30/–20%	1820		B65839A0000R057
T65	3000 +30/–20%	3640		B65839A0000R065
T38	5200 +40/–30%	6310		B65839A0000Y038
N87	1100 +30/–20%	1330	< 0.08 (200 mT, 100 kHz, 100 °C)	B65839A0000R087

Other A_L values/air gaps and materials available on request – see Processing remarks on page 7.

Coil former

Material: GFR thermosetting plastic (UL 94 V-0, insulation class to IEC 60085:

F $\triangleq$ max. operating temperature 155 °C)

Sumikon PM 9630® [E41429 (M)], color code black,

SUMITOMO BAKELITE CO LTD

Solderability: to IEC 60068-2-20, test Ta, method 1 (aging 3): 235 °C, 2 s

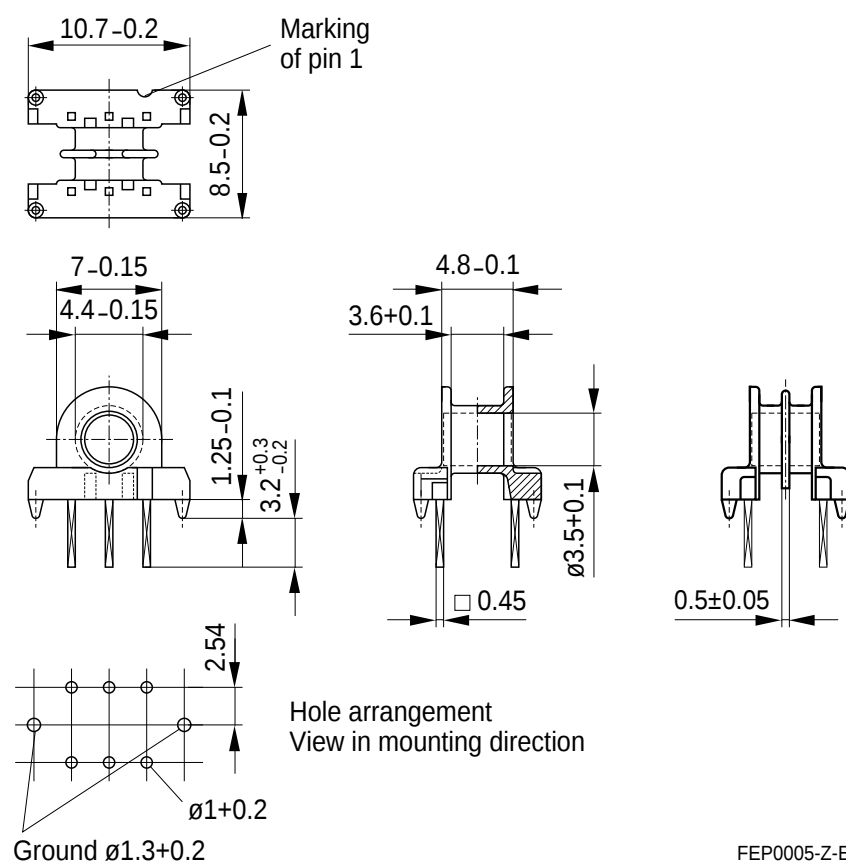
Resistance to soldering heat: to IEC 60068-2-20, test Tb, method 1B: 350 °C, 3.5 s

Winding: see Processing notes, 2.1

Pins: Squared pins

Coil former					Ordering code
Sections	A _N mm ²	l _N mm	A _R value μΩ	Terminals	
1	4.7	17.7	128.7	6	B65840B1006D001
2	4.2	17.7	143.8	6	B65840C1006D002

Coil former



FEP0005-Z-E



SMD coil former with gullwing terminals

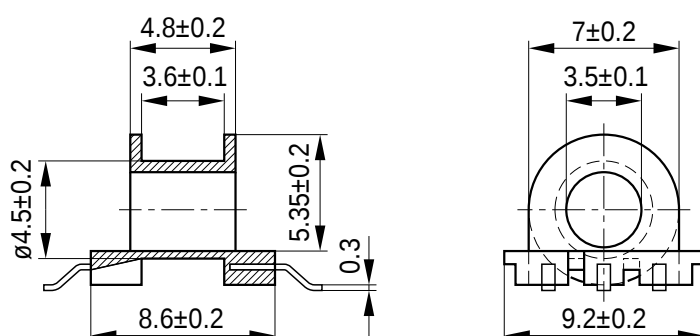
Material: GFR liquid crystal polymer (UL 94 V-0), color code black

Sumika Super E4008® [E54705 (M)], SUMITOMO CHEMICAL CO LTD

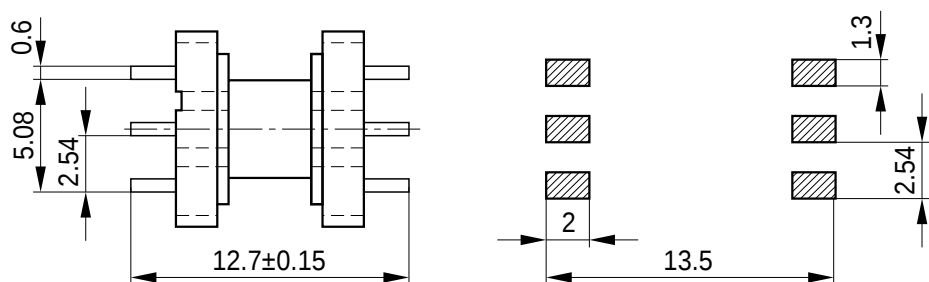
Solderability: to IEC 60068-2-58, test Td, method 6 (Group 3): 245 °C, 3 s

Resistance to soldering heat: to IEC 60068-2-58, test Td, method 6 (Group 3): 255 °C, 10 s
permissible soldering temperature for wire-wrap connection on coil former: 400 °C, 1 s

Sections	A _N mm ²	l _N mm	A _R value μΩ	Terminals	Ordering code
1	4.5	18.1	138.1	6	B65840N1106T001



Recommended
PCB layout



FEK0475-T-E



Coil former

Material: GFR liquid crystal polymer (UL 94 V-0, insulation class to IEC 60085:

F = max. operating temperature 155°C), color code black

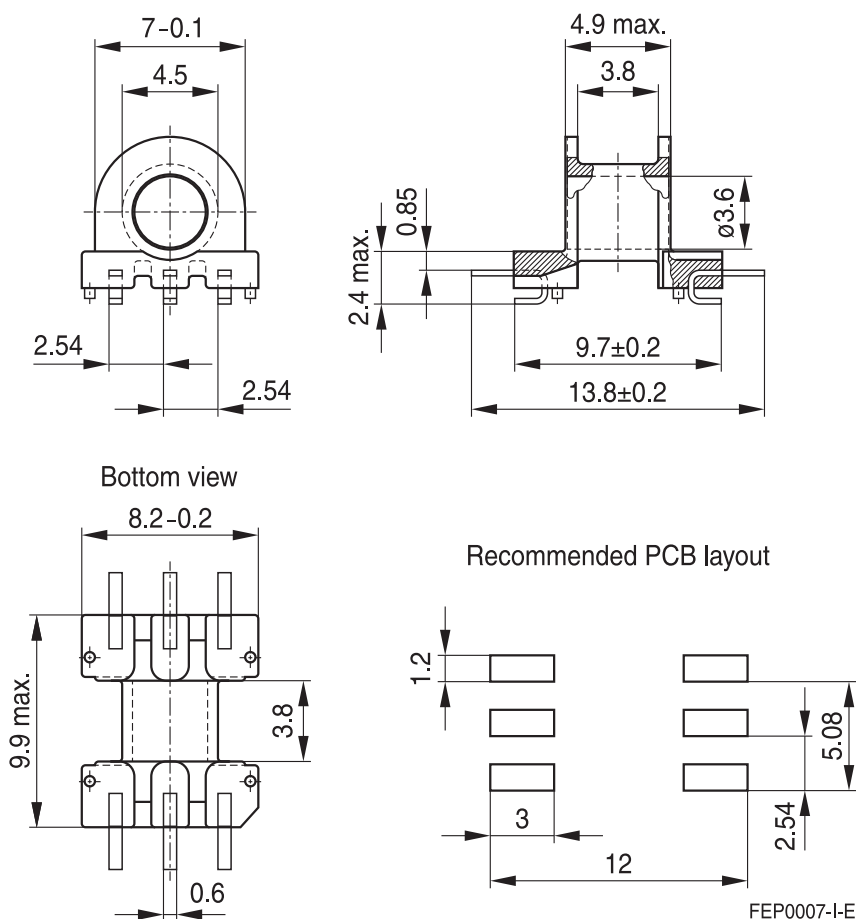
Sumika Super E4008 [E54705 (M)], SUMITOMO CHEMICAL CO LTD

Solderability: IEC 60068-2-58, test Td, method 6 (Group 3): 245 °C, 3 s

Resistance to soldering heat: to IEC 60068-2-58, test Td, method 6 (Group 3): 255 °C, 10 s

permissible soldering temperature for wire-wrap connection on coil former: 400 °C, 1 s

Sections	A_N mm ²	l_N mm	A_R value $\mu\Omega$	Terminals	Ordering code
1	4.7	18	132.9	6	B65840H1106T001



Ferrites and accessories

Cautions and warnings

Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembling and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of the special behavior under mechanical load.

As valid for any ceramic material, ferrite cores are brittle and sensitive to any shock, fast temperature changing or tensile load. Especially high cooling rates under ultrasonic cleaning and high static or cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see data book, chapter “*General - Definitions, 8.1*”.

Effects of core combination on A_L value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower is the value for the initial permeability. Thus the embedding medium should have the greatest possible elasticity.

For detailed information see data book, chapter “*General - Definitions, 8.1*”.

Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

NiZn-materials

The magnetic properties of NiZn-materials can change irreversible in high magnetic fields.

Ferrite Accessories

Our ferrite accessories have been designed and evaluated only in combination with our ferrite cores. We explicitly point out that our ferrite accessories or our ferrite cores may not be compatible with those of other manufacturers. Any such combination requires prior testing by the customer and will be at the customer's own risk.

We assume no warranty or reliability for the combination of our ferrite accessories with cores and other accessories from any other manufacturer.

Processing remarks

The start of the winding process should be soft. Else the flanges may be destroyed.

- Too strong winding forces may blast the flanges or squeeze the tube that the cores can not be mounted any more.
- Too long soldering time at high temperature (>300 °C) may effect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability problems at the transformer because of pollution with Sn oxyde of the tin bath or burned insulation of the wire. For detailed information see chapter “*Processing notes*”, section 2.2.
- The dimensions of the hole arrangement have fixed values and should be understood as a recommendation for drilling the printed circuit board. For dimensioning the pins, the group of holes can only be seen under certain conditions, as they fit into the given hole arrangement. To avoid problems when mounting the transformer, the manufacturing tolerances for positioning the customers' drilling process must be considered by increasing the hole diameter.

Ferrites and accessories

Cautions and warnings

Display of ordering codes for TDK Electronics products

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Ferrites and accessories

Symbols and terms

Symbol	Meaning	Unit
A	Cross section of coil	mm ²
A _e	Effective magnetic cross section	mm ²
A _L	Inductance factor; $A_L = L/N^2$	nH
A _{L1}	Minimum inductance at defined high saturation ($\cong \mu_a$)	nH
A _{min}	Minimum core cross section	mm ²
A _N	Winding cross section	mm ²
A _R	Resistance factor; $A_R = R_{Cu}/N^2$	$\mu\Omega = 10^{-6} \Omega$
B	RMS value of magnetic flux density	Vs/m ² , mT
ΔB	Flux density deviation	Vs/m ² , mT
$\hat{B}$	Peak value of magnetic flux density	Vs/m ² , mT
$\Delta \hat{B}$	Peak value of flux density deviation	Vs/m ² , mT
B _{DC}	DC magnetic flux density	Vs/m ² , mT
B _R	Remanent flux density	Vs/m ² , mT
B _S	Saturation magnetization	Vs/m ² , mT
C ₀	Winding capacitance	F = As/V
CDF	Core distortion factor	mm ^{-4.5}
DF	Relative disaccommodation coefficient $DF = d/\mu_i$	
d	Disaccommodation coefficient	
E _a	Activation energy	J
f	Frequency	s ⁻¹ , Hz
f _{cutoff}	Cut-off frequency	s ⁻¹ , Hz
f _{max}	Upper frequency limit	s ⁻¹ , Hz
f _{min}	Lower frequency limit	s ⁻¹ , Hz
f _r	Resonance frequency	s ⁻¹ , Hz
f _{Cu}	Copper filling factor	
g	Air gap	mm
H	RMS value of magnetic field strength	A/m
$\hat{H}$	Peak value of magnetic field strength	A/m
H _{DC}	DC field strength	A/m
H _c	Coercive field strength	A/m
h	Hysteresis coefficient of material	10 ⁻⁶ cm/A
h/ μ_i^2	Relative hysteresis coefficient	10 ⁻⁶ cm/A
I	RMS value of current	A
I _{DC}	Direct current	A
$\hat{I}$	Peak value of current	A
J	Polarization	Vs/m ²
k	Boltzmann constant	J/K
k ₃	Third harmonic distortion	
k _{3c}	Circuit third harmonic distortion	
L	Inductance	H = Vs/A

Ferrites and accessories

Symbols and terms

Symbol	Meaning	Unit
$\Delta L/L$	Relative inductance change	H
L_0	Inductance of coil without core	H
L_H	Main inductance	H
L_p	Parallel inductance	H
L_{rev}	Reversible inductance	H
L_s	Series inductance	H
l_e	Effective magnetic path length	mm
l_N	Average length of turn	mm
N	Number of turns	
P_{Cu}	Copper (winding) losses	W
P_{trans}	Transferrable power	W
P_V	Relative core losses	mW/g
PF	Performance factor	
Q	Quality factor ($Q = \omega L/R_s = 1/\tan \delta_L$)	
R	Resistance	Ω
R_{Cu}	Copper (winding) resistance ($f = 0$)	Ω
R_h	Hysteresis loss resistance of a core	Ω
ΔR_h	R_h change	Ω
R_i	Internal resistance	Ω
R_p	Parallel loss resistance of a core	Ω
R_s	Series loss resistance of a core	Ω
R_{th}	Thermal resistance	K/W
R_V	Effective loss resistance of a core	Ω
s	Total air gap	mm
T	Temperature	$^{\circ}\text{C}$
ΔT	Temperature difference	K
T_C	Curie temperature	$^{\circ}\text{C}$
t	Time	s
t_v	Pulse duty factor	
$\tan \delta$	Loss factor	
$\tan \delta_L$	Loss factor of coil	
$\tan \delta_r$	(Residual) loss factor at $H \rightarrow 0$	
$\tan \delta_e$	Relative loss factor	
$\tan \delta_h$	Hysteresis loss factor	
$\tan \delta/\mu_i$	Relative loss factor of material at $H \rightarrow 0$	
U	RMS value of voltage	V
$\hat{U}$	Peak value of voltage	V
V_e	Effective magnetic volume	mm^3
Z	Complex impedance	Ω
Z_n	Normalized impedance $ Z _n = Z /N^2 \times \varepsilon (l_e/A_e)$	Ω/mm

Ferrites and accessories

Symbols and terms

Symbol	Meaning	Unit
α	Temperature coefficient (TK)	1/K
α_F	Relative temperature coefficient of material	1/K
α_e	Temperature coefficient of effective permeability	1/K
ε_r	Relative permittivity	
Φ	Magnetic flux	Vs
η	Efficiency of a transformer	
η_B	Hysteresis material constant	mT ⁻¹
η_i	Hysteresis core constant	A ⁻¹ H ^{-1/2}
λ_s	Magnetostriction at saturation magnetization	
μ	Relative complex permeability	
μ_0	Magnetic field constant	Vs/Am
μ_a	Relative amplitude permeability	
μ_{app}	Relative apparent permeability	
μ_e	Relative effective permeability	
μ_i	Relative initial permeability	
μ_p'	Relative real (inductive) component of $\bar{\mu}$ (for parallel components)	
μ_p''	Relative imaginary (loss) component of $\bar{\mu}$ (for parallel components)	
μ_r	Relative permeability	
μ_{rev}	Relative reversible permeability	
μ_s'	Relative real (inductive) component of $\bar{\mu}$ (for series components)	
μ_s''	Relative imaginary (loss) component of $\bar{\mu}$ (for series components)	
μ_{tot}	Relative total permeability derived from the static magnetization curve	
ρ	Resistivity	Ωm^{-1}
$\Sigma l/A$	Magnetic form factor	mm ⁻¹
τ_{Cu}	DC time constant $\tau_{Cu} = L/R_{Cu} = A_L/A_R$	s
ω	Angular frequency; $\omega = 2\pi f$	s ⁻¹

All dimensions are given in mm.

SMD Surface-mount device

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Release 2024-02